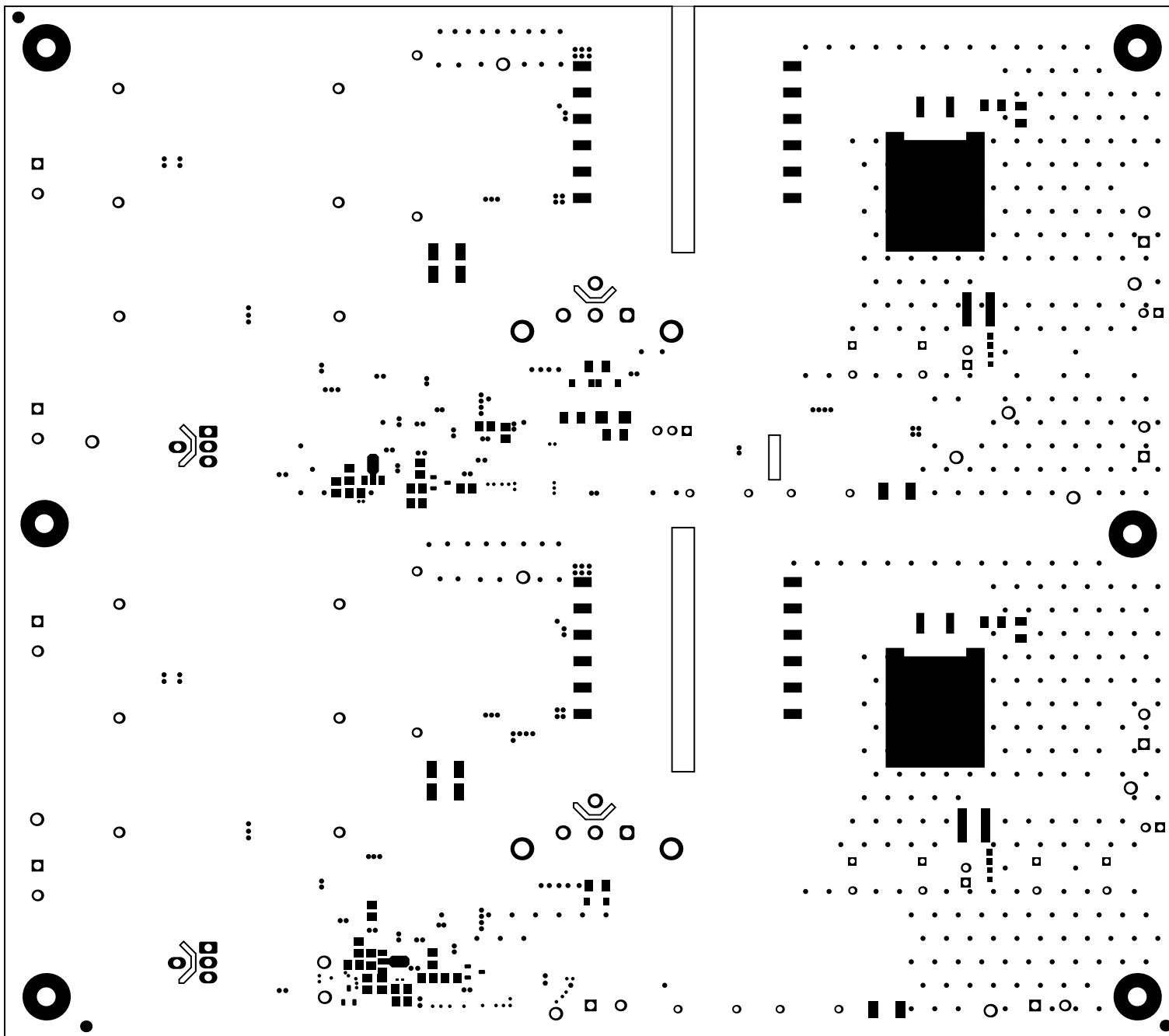
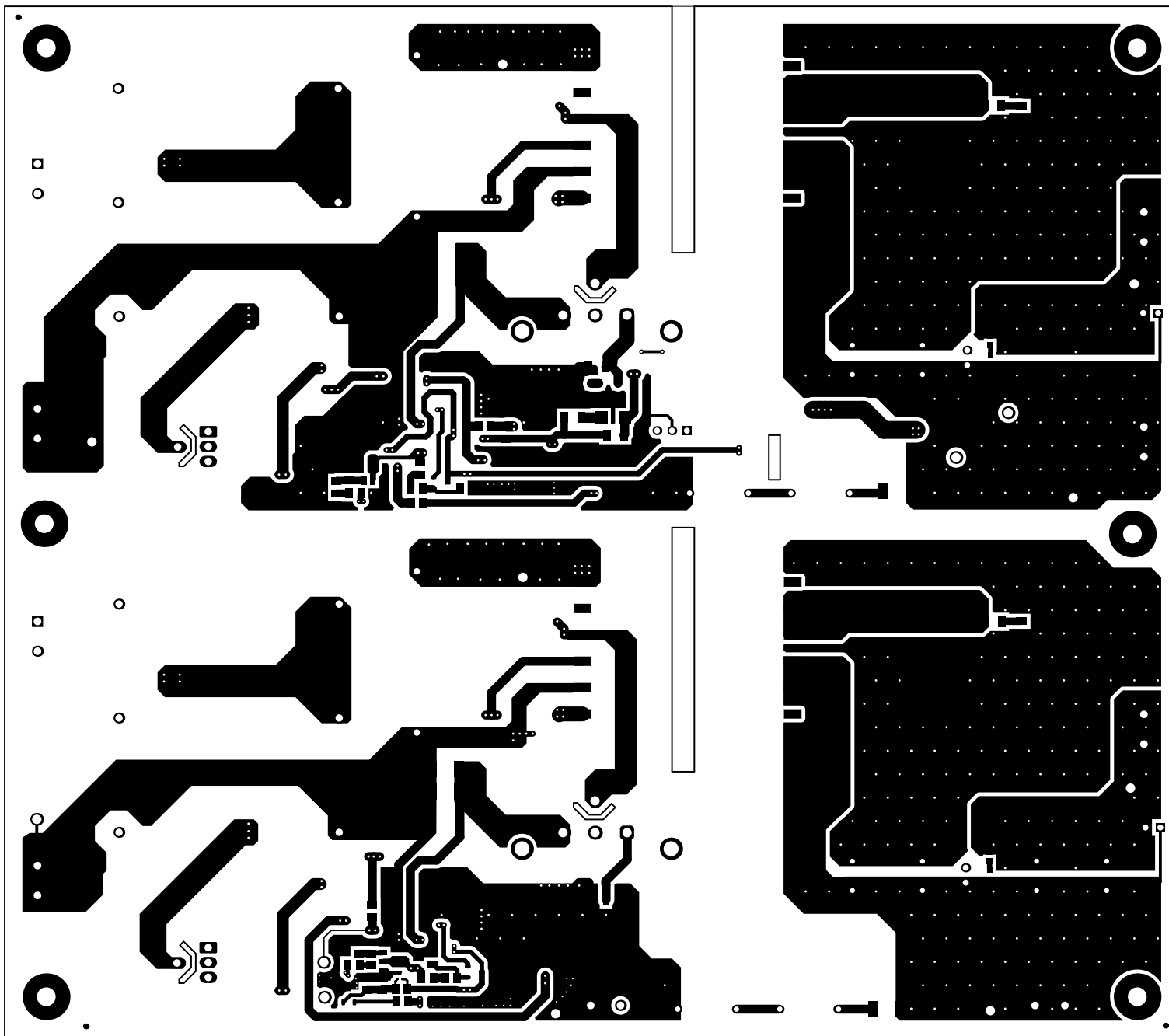


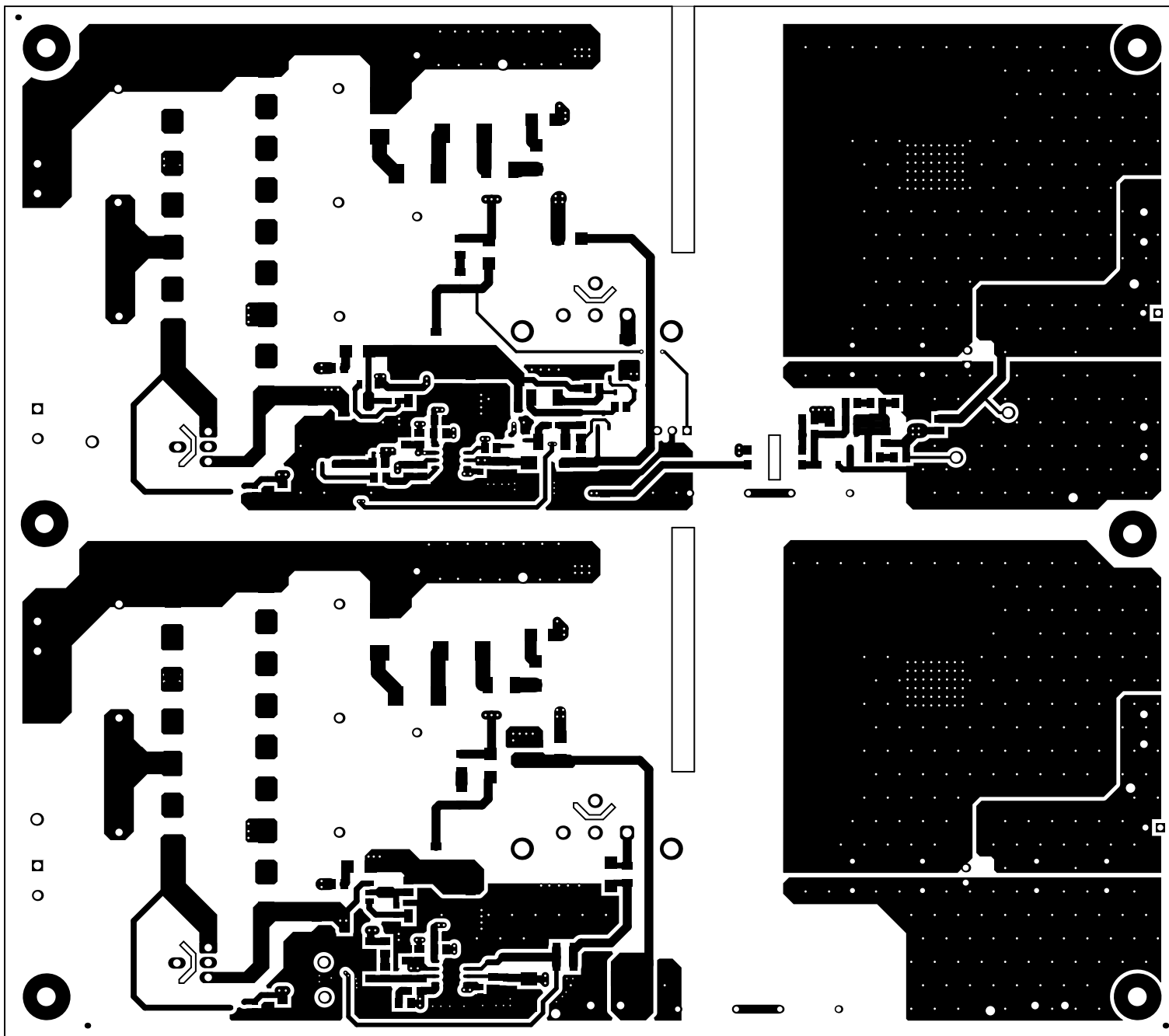
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01505		
PLOT NAME = Top Overlay	GENERATED : 12/28/2017 4:02:36 PM	TEXAS INSTRUMENTS	



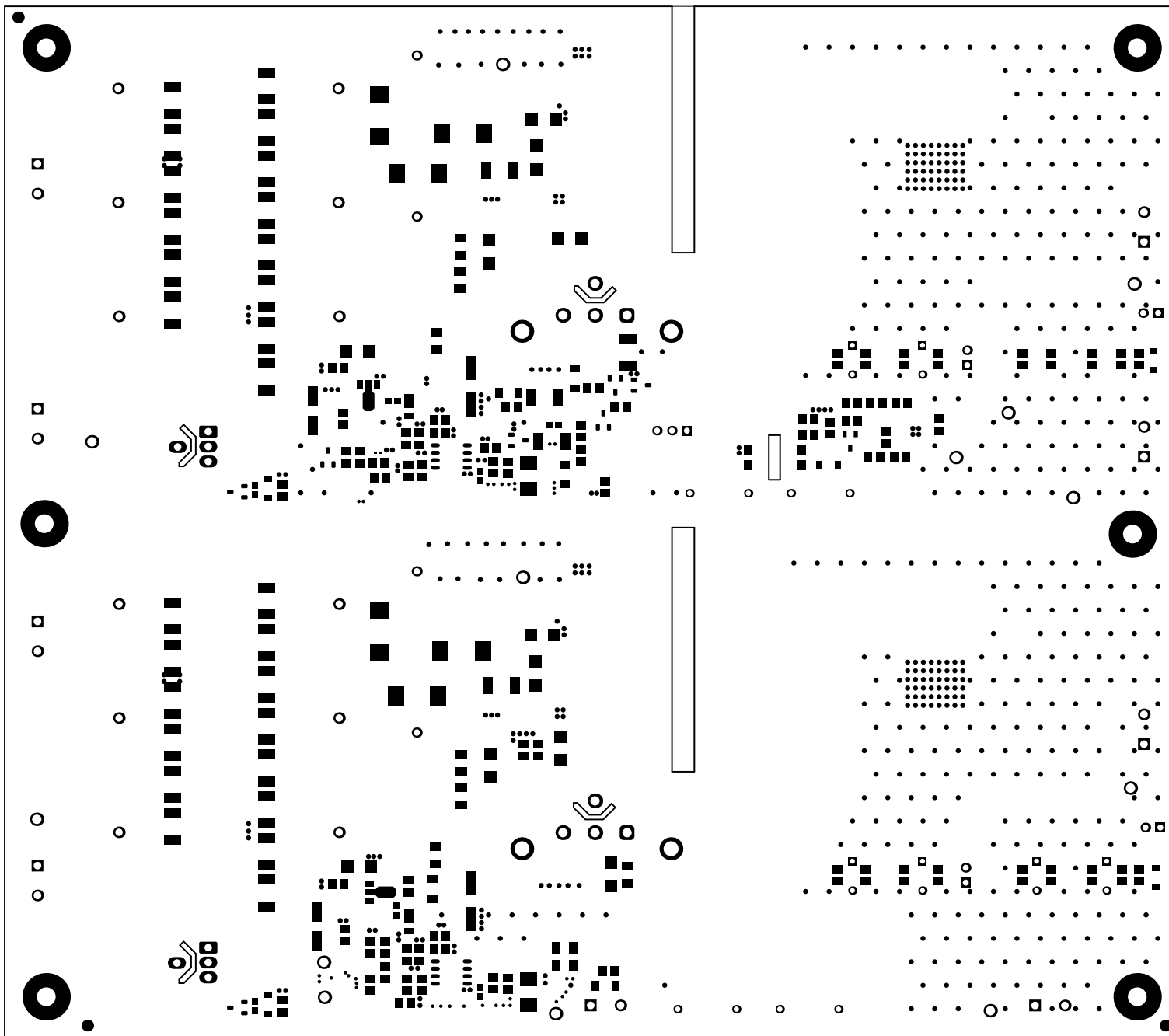
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01505		
PLOT NAME = Top Solder Mask	GENERATED : 12/28/2017 4:02:37 PM	TEXAS INSTRUMENTS	



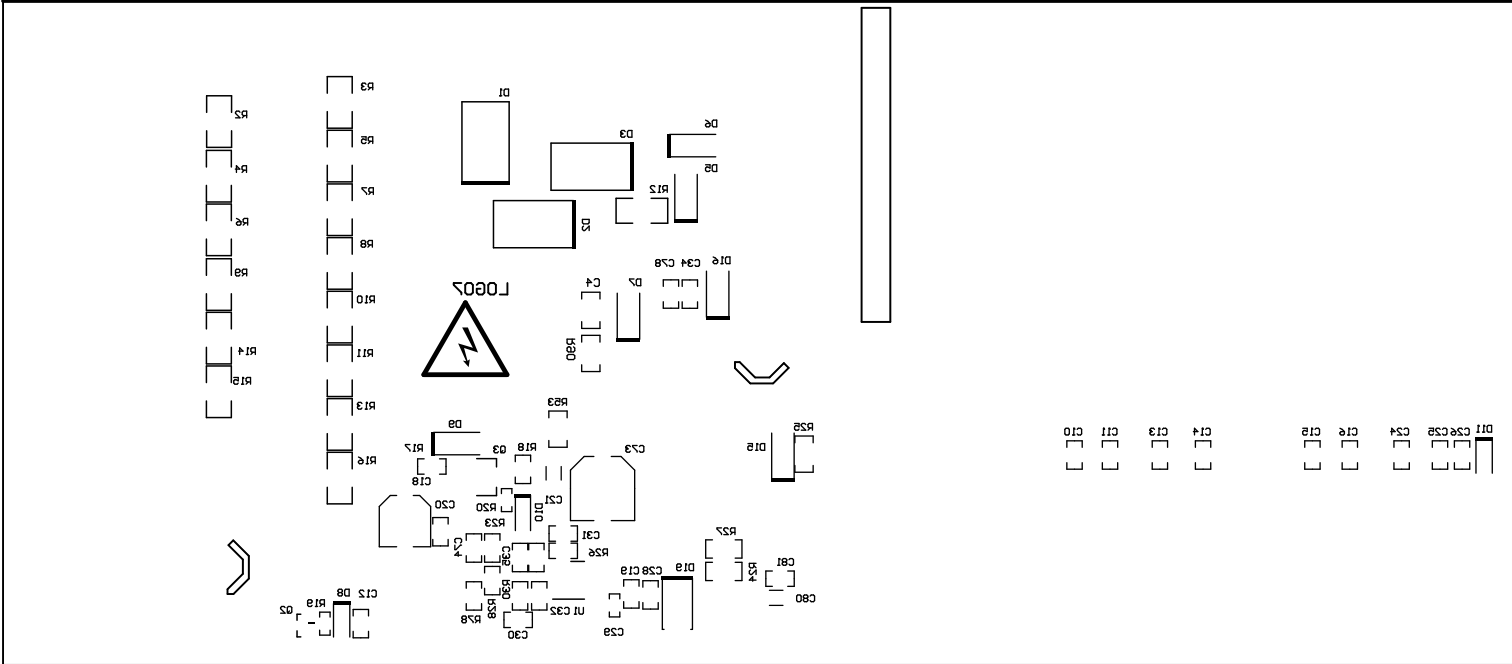
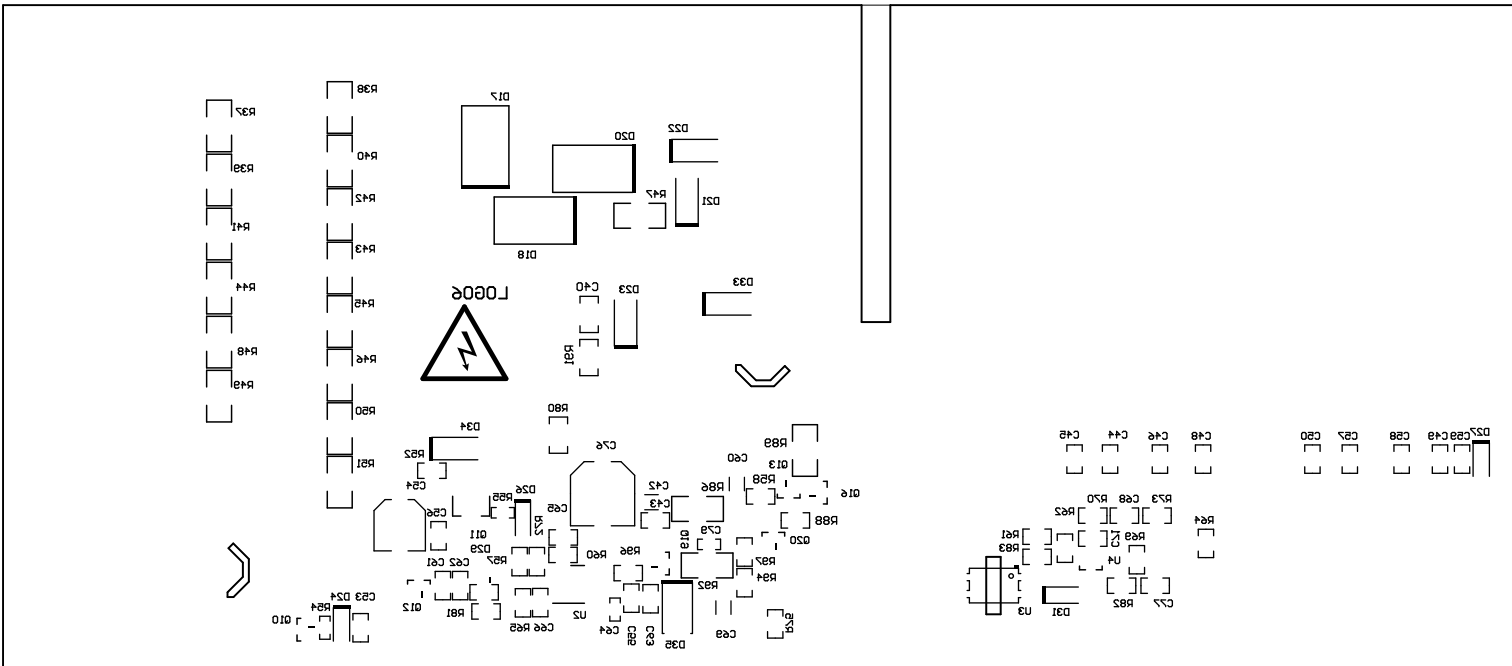
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01505		
PLOT NAME = Top Layer	GENERATED : 12/28/2017 4:02:38 PM	TEXAS INSTRUMENTS	



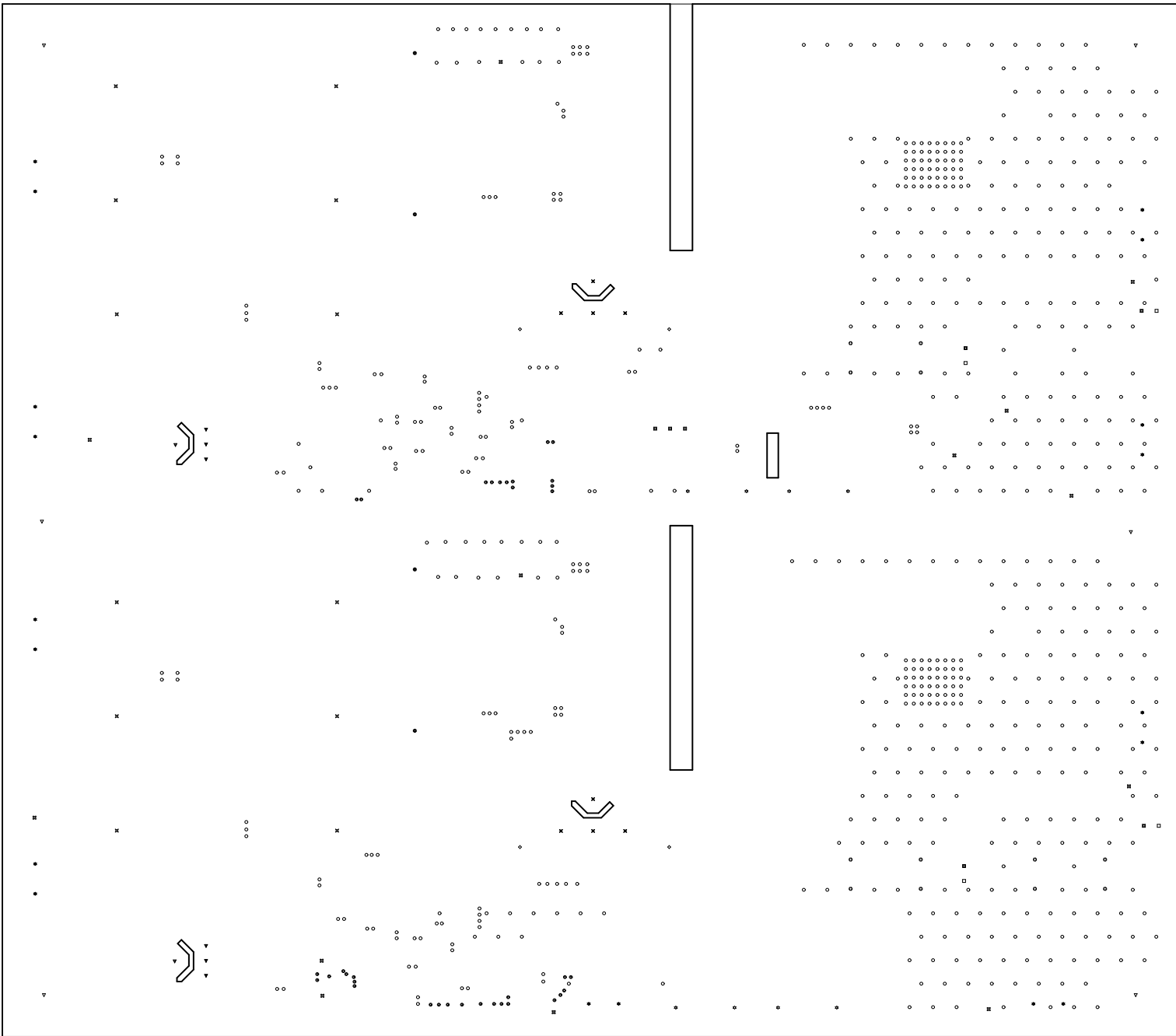
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01505		
PLOT NAME = Bottom Layer	GENERATED : 12/28/2017 4:02:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01505		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/28/2017 4:02:40 PM	TEXAS INSTRUMENTS	

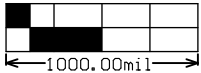
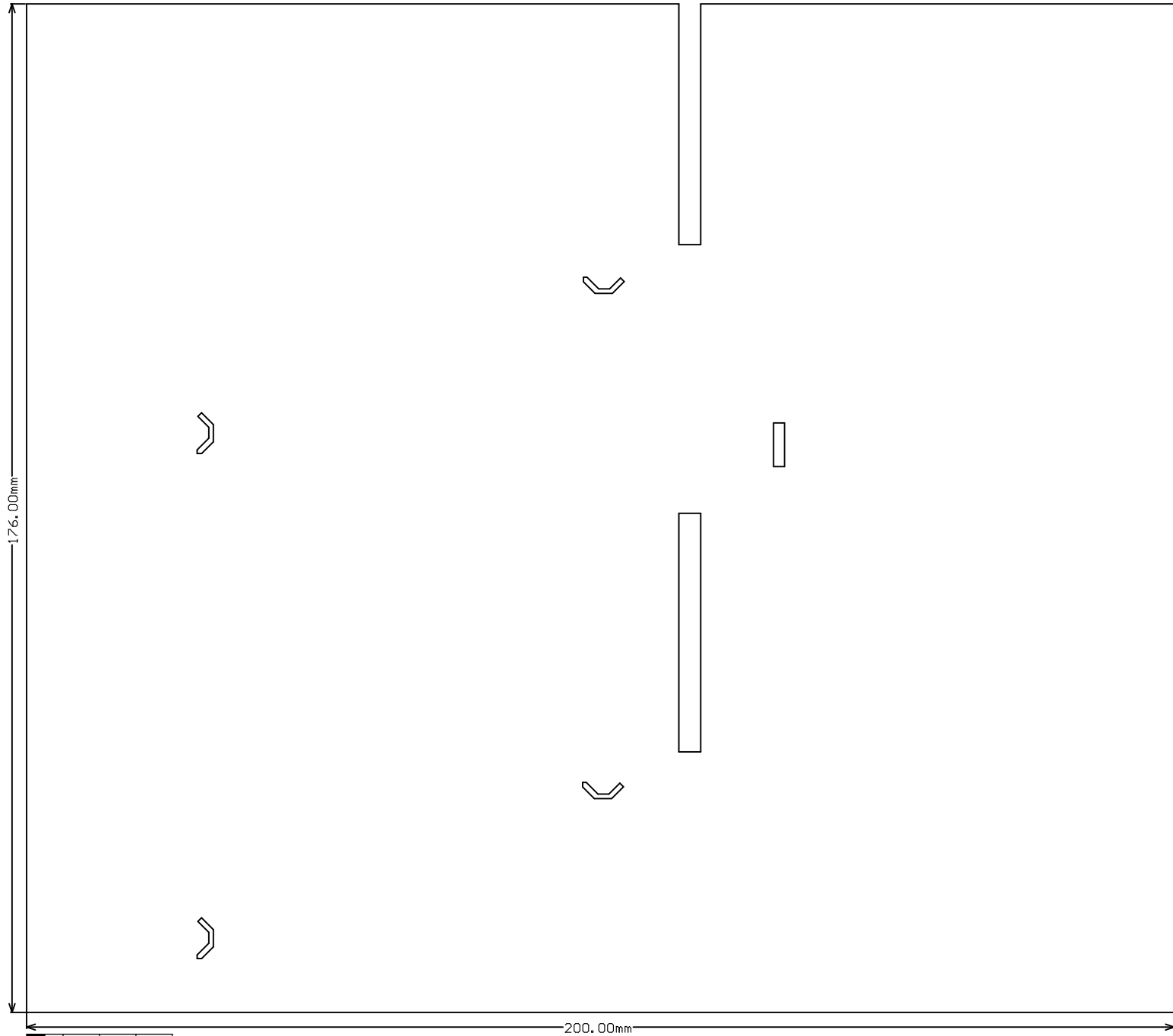


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01505		
PLOT NAME = Bottom Overlay	GENERATED : 12/28/2017 4:02:41 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Placed	Hole Type	Drill Layer Pair	Use Pad	Pad Shape	Template	Description	Hole Tolerance	Pad Tolerance
□	4	10.00mil (1.010mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rectangle	slDrill02			
○	4	49.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	C68Drill02			
◇	4	100.38mil (2.550mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	C68Drill05			
○	5	126.38mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	C68Drill05			
○	5	38.43mil (0.975mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	8	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	8	62.00mil (1.575mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	12	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	12	46.21mil (1.170mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	13	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	18	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	cl19Drill02			
○	36	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Use	Rounded	cl19Drill02			
○	674	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	Use	Rounded	cl19Drill02			
○	US Total										

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01505		
PLOT NAME = Drill Drawing	GENERATED : 12/28/2017 4:02:42 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01505	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01505		
PLOT NAME = Board Dimensions	GENERATED : 12/28/2017 4:02:44 PM	TEXAS INSTRUMENTS	



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